



INTAGLIO PRINT COPPER PLATING PRODUCTS



Commodity Name

HN-600 HARD COPPER PLATING PROCESS



Bath Composition and Working Conditions

Copper Sulfate	200~280g/L
Pure Sulfuric Acid	55~70g/L
Chloride Ion	80~150mg/L
Solid Copper Brightener HN-602	2~3mL/L
Solid copper Make up Solution HN-603	4~6ml/L
Temperature	35~45
Current Density in Cathode	15~30 A/dm ²
Anode	Phosphorous copper
Area ratio of Cathode and Anode	1:4-8
Immersion Degree	Completely immersion or semi-immersion
Filtration	Continuous filtration

• Consumption:

Solid Copper AdditiveHN-601	80-120mL/1000A.H
Solid Copper Brightener HN-602	80-120mL/1000A.H
Solid Copper Make up Solution HN-603	40-50mL/1000A.H



Application and Advantage

- 1.The layer is in fine grained structure, and has high-temperature resistance.
- 2.The layer has excellent anti-oxidation and anti-tarnish ability.
- 3.The hardness of deposit is spread evenly, can keep for months without change.
- 4.The hardness of deposit is 180~220HV, is beneficial to obtain good intaglio print.
- 5.The deposit surface is smooth after plating, good overall performance. It can save polishing time.
- 6.It is suitable for intaglio print copper plating. Dissolved while electrolyzing, which reduces the make-up solution yield.



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